TOSHIBA FIELD EFFECT TRANSISTOR SILICON P CHANNEL MOS TYPE (L^2-π-MOSⅣ)

2SJ304

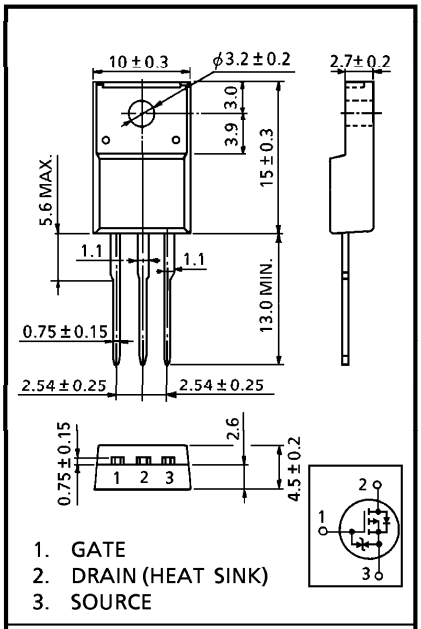
HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS

DC-DC CONVERTER, RELAY DRIVE AND MOTOR DRIVE APPLICATIONS

INDUSTRIAL APPLICATIONS

- 4 V Gate Drive
- Low Drain-Source ON Resistance : $R_{DS\,(ON)} = 80\,m\Omega$ (Typ.)
- High Forward Transfer Admittance : $|Y_{fs}| = 8.0\,S$ (Typ.)
- Low Leakage Current : $I_{DSS} = -100\,\mu A$ (Max.) ($V_{DS} = -60\,V$)
- Enhancement-Mode : $V_{th} = -0.8 \sim -2.0\,V$ ($V_{DS} = -10\,V$, $I_D = -1\,mA$)

Unit in mm



JEDEC	—
EIAJ	SC-67
TOSHIBA	2-10R1B

Weight : 1.9 g

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	RATING	UNIT
Drain-Source Voltage		V_{DSS}	−60	V
Drain-Gate Voltage ($R_{GS} = 20\,k\Omega$)		V_{DGR}	−60	V
Gate-Source Voltage		V_{GSS}	±20	V
Drain Current	DC	I_D	−14	A
	Pulse	I_{DP}	−56	
Drain Power Dissipation (Tc = 25°C)		P_D	40	W
Channel Temperature		T_{ch}	150	°C
Storage Temperature Range		T_{stg}	−55~150	°C

THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	$R_{th(ch-c)}$	3.125	°C / W
Thermal Resistance, Channel to Ambient	$R_{th(ch-a)}$	62.5	°C / W

This transistor is an electrostatic sensitivedevice.
Please handle with caution.

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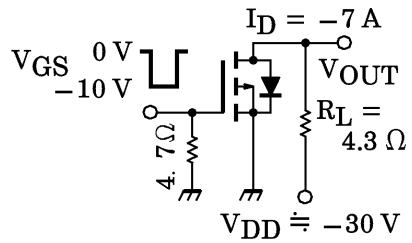
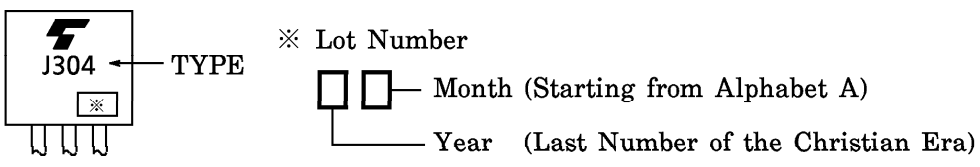
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage Current		I_{GSS}	$V_{GS} = \pm 16$ V, $V_{DS} = 0$ V	—	—	±10	μA
Drain Cut-off Current		I_{DSS}	$V_{DS} = -60$ V, $V_{GS} = 0$ V	—	—	−100	μA
Drain-Source Breakdown Voltage		$V_{(BR)DSS}$	$I_D = -10$ mA, $V_{GS} = 0$ V	−60	—	—	V
Gate Threshold Voltage		V_{th}	$V_{DS} = -10$ V, $I_D = -1$ mA	−0.8	—	−2.0	V
Drain-Source ON Resistance		$R_{DS(ON)}$	$V_{GS} = -4$ V, $I_D = -5$ A	—	130	190	mΩ
			$V_{GS} = -10$ V, $I_D = -7$ A	—	80	120	
Forward Transfer Admittance		$\|Y_{fs}\|$	$V_{DS} = -10$ V, $I_D = -7$ A	5.0	8.0	—	S
Input Capacitance		C_{iss}	$V_{DS} = -10$ V, $V_{GS} = 0$ V, f = 1 MHz	—	1200	—	pF
Reverse Transfer Capacitance		C_{rss}		—	220	—	
Output Capacitance		C_{oss}		—	550	—	
Switching Time	Rise Time	t_r		—	20	—	ns
	Turn-on Time	t_{on}		—	30	—	
	Fall Time	t_f		—	25	—	
	Turn-off Time	t_{off}	V_{IN} : t_r, $t_f < 5$ ns, Duty ≦ 1%, $t_w = 10$ μs	—	100	—	
Total Gate Charge (Gate-Source Plus Gate-Drain)		Q_g	$V_{DD} \fallingdotseq -48$ V, $V_{GS} = -10$ V, $I_D = -14$A	—	45	—	nC
Gate-Source Charge		Q_{gs}		—	30	—	
Gate-Drain ("Miller") Charge		Q_{gd}		—	15	—	

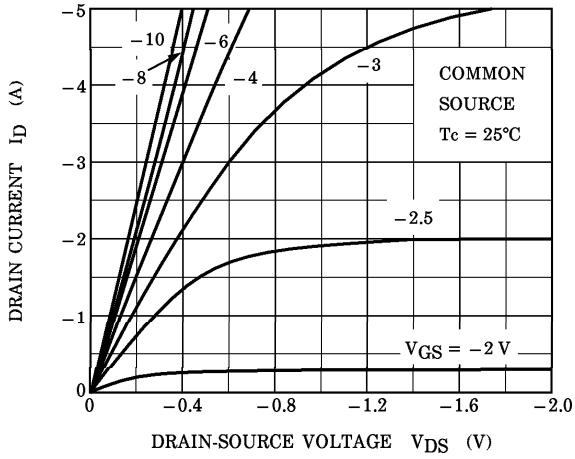
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	I_{DR}	—	—	—	−14	A
Pulse Drain Reverse Current	I_{DRP}	—	—	—	−56	A
Diode Forward Voltage	V_{DSF}	$I_{DR} = -14$ A, $V_{GS} = 0$ V	—	—	1.7	V
Reverse Recovery Time	t_{rr}	$I_{DR} = -14$ A, $V_{GS} = 0$ V, $dI_{DR}/dt = 50$ A/μs	—	110	—	ns
Reverse Recovered Charge	Q_{rr}		—	0.18	—	μC

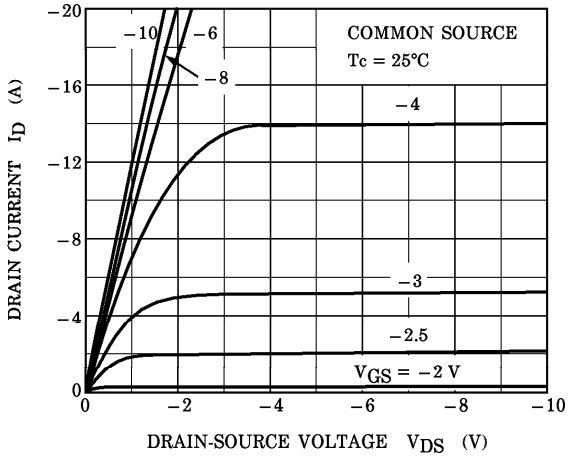
MARKING



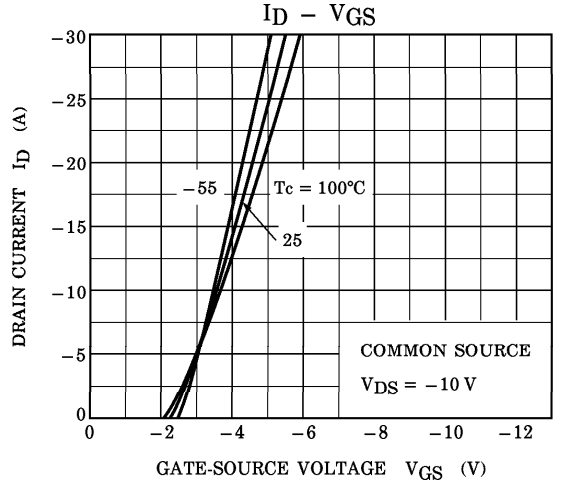
$I_D - V_{DS}$



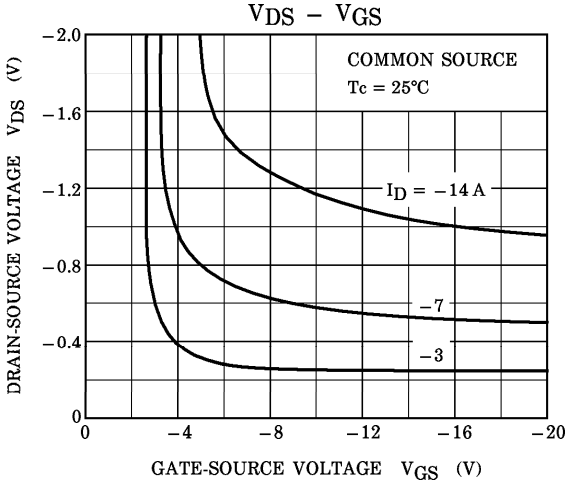
$I_D - V_{DS}$



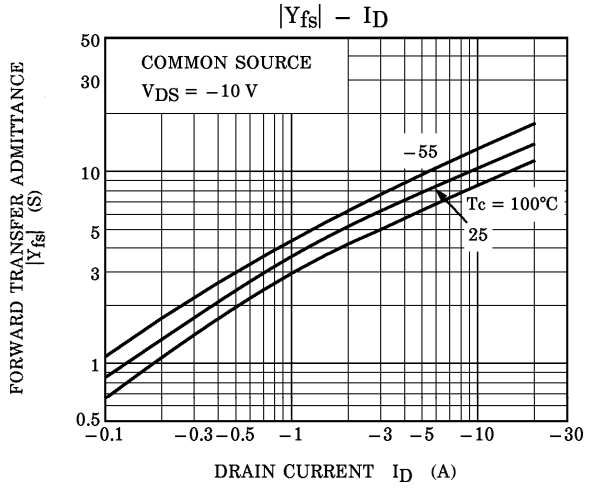
$I_D - V_{GS}$



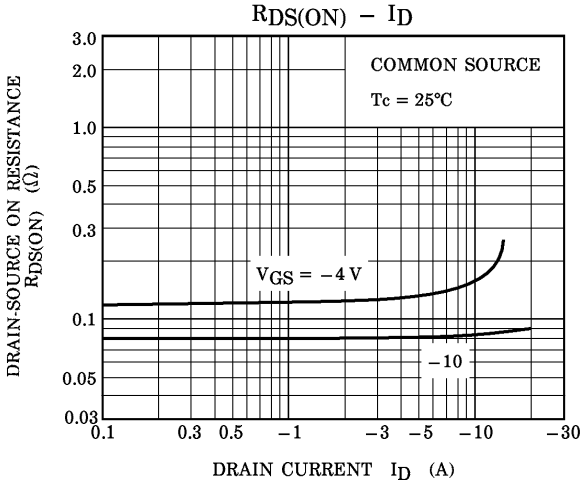
$V_{DS} - V_{GS}$



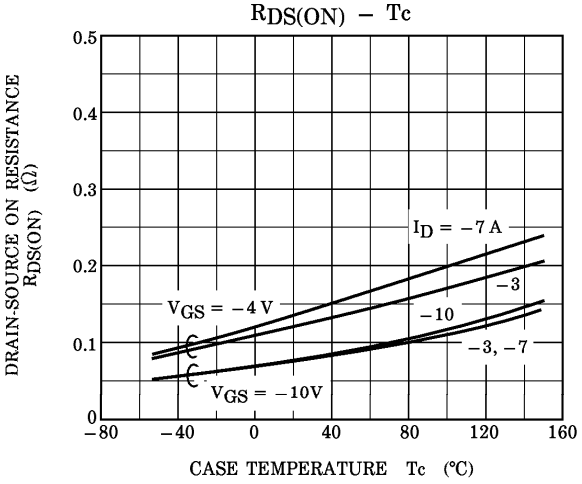
$|Y_{fs}| - I_D$



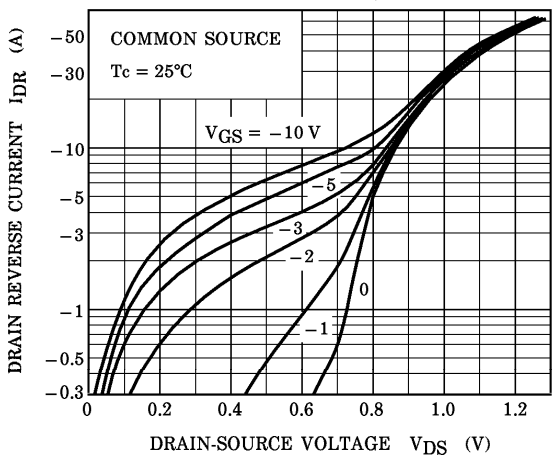
$R_{DS(ON)} - I_D$



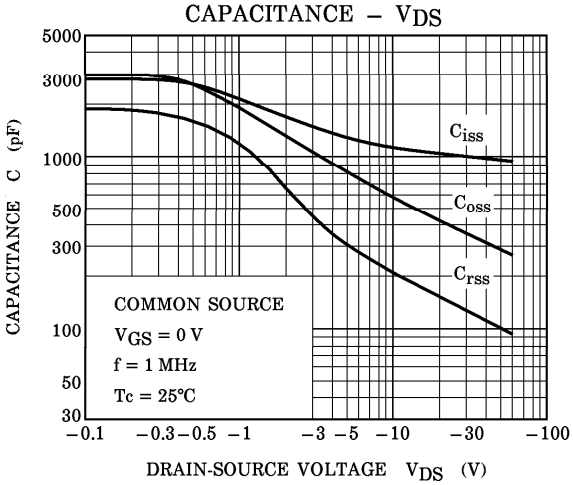
$R_{DS(ON)}$ – Tc



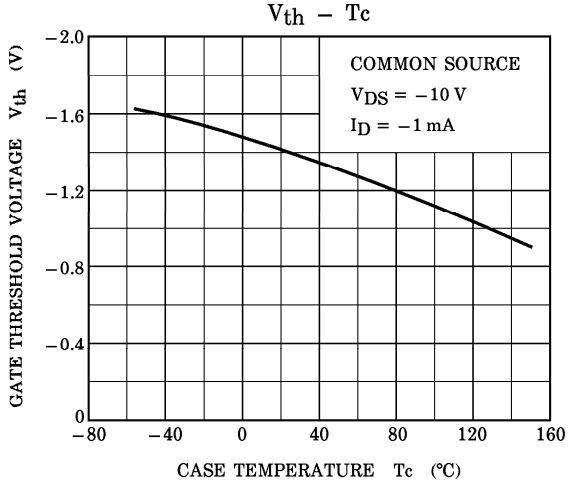
I_{DR} – V_{DS}



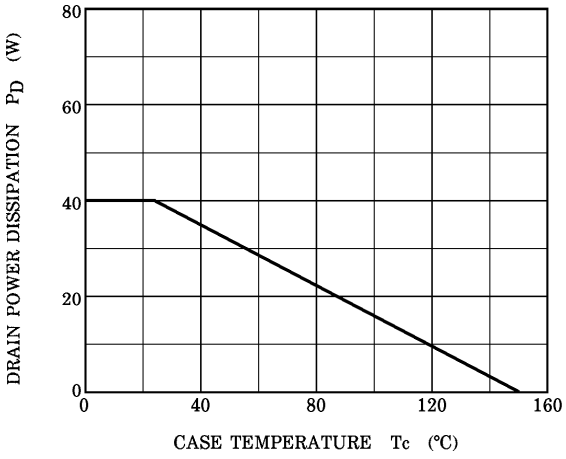
CAPACITANCE – V_{DS}



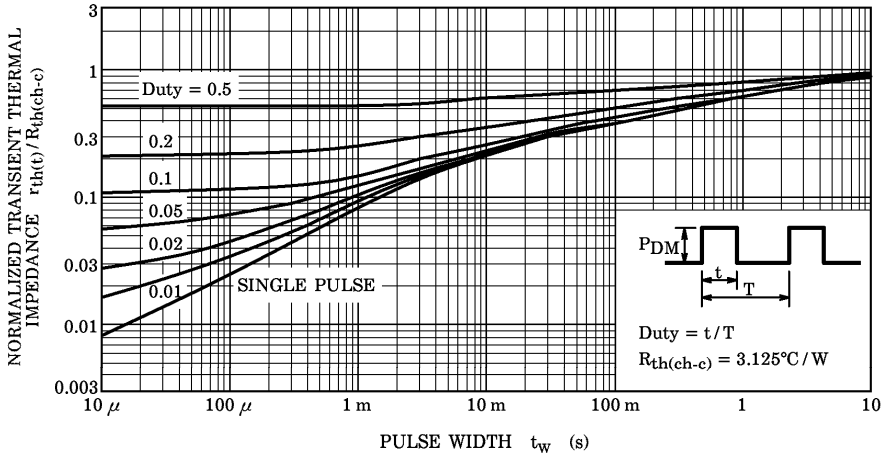
V_{th} – Tc



P_D – Tc



r_{th} – t_w



SAFE OPERATING AREA